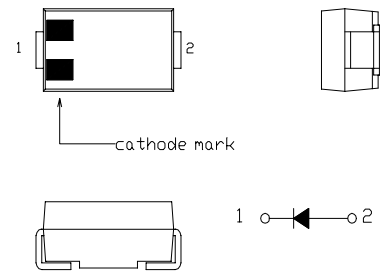


SBD Type : EC21QS10

FEATURES

- * Miniature Size, Surface Mount Device
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 30 Volts through 100Volts Types Available
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight: 0.06g

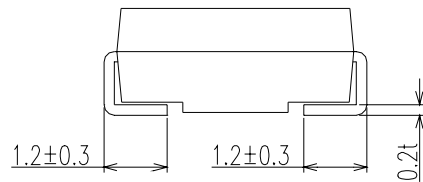
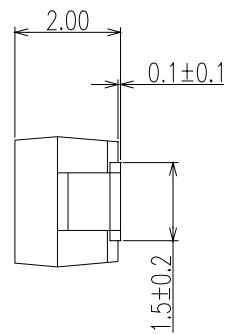
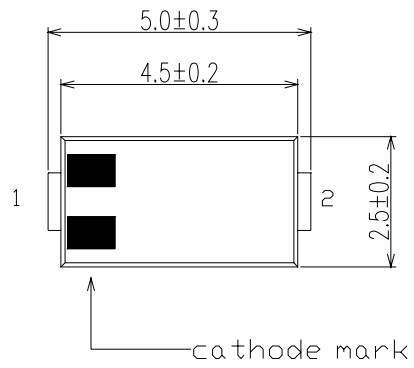
Rating	Symbol	EC21QS10			Unit
Repetitive Peak Reverse Voltage	V _{RRM}	100			V
Average Rectified Output Current	I _o	1.3	Ta=25 °C *1	50Hz Half Sine	A
		2.0	Tl=106 °C	Wave Resistive Load	
RMS Forward Current	I _{F(RMS)}	3.14			A
Surge Forward Current	I _{FSM}	50	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T _{jw}	-40 to +150			°C
Storage Temperature Range	T _{stg}	-40 to +150			°C

Electrical • Thermal Characteristics

Characteristics		Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current		I_{RM}	$T_j = 25\text{ }^{\circ}\text{C}$, $V_{RM} = V_{RRM}$	-	-	1	mA
Peak Forward Voltage		V_{FM}	$T_j = 25\text{ }^{\circ}\text{C}$, $I_{FM} = 2.0\text{A}$	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	Alumina Substrate Mounted *1	-	-	108	$^{\circ}\text{C}/\text{W}$
	Junction to Lead	$R_{th(j-l)}$	-	-	-	23	

*1 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)
(T_l : Lead Temperature)

EC21QS10 OUTLINE DRAWING (Dimensions in mm)



soldering pad

